

P-Channel Logic Level Enhancement Mode Power MOSFET

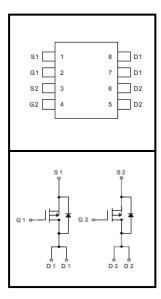
FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Load Switch
- Power Management
- Pulse Width Modulation(PWM)





Device Marking and Package Information						
Device	Package	Marking				
CTS03PP055	Sop-8	CTS03PP055				

Absolute Maximum Ratings at T _j = 25°C unless otherwise noted							
Parameter		Symbol	Value	Unit			
Drain-Source Voltage (V _{GS} = 0V)		V _{DSS}	-30	V			
Continuous Drain Current T _C = 25°C	(note1)	,	-5.1				
Continuous Drain Current T _C = 100°C	(note1)	I _D	-3.2	A			
Pulsed Drain Current	(note2)	I _{DM}	-21	А			
Gate Source Voltage		V _{GSS}	±20	V			
Power Dissipation T _C = 25°C	(note4)	P _D	2.5	W			
Single Pulse Avalanche Energy	(note3)	E _{AS}	28	mJ			
Operating Junction and Storage Temperatu	ıre Range	T _J , T _{stg}	-55~+175	°C			

Thermal Characteristics				
Parameter		Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	(note1)	$R_{\theta JA}$	58	°C/W



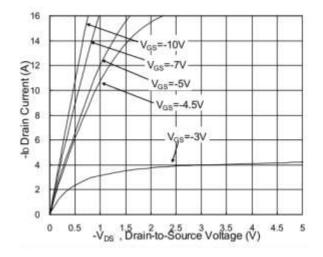
Electrical Characteristics T _j = 25°C unless otherwise specified										
Para santa s		Total Octobrilla								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit				
Static										
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = -250\mu A$	-30			V				
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			-1	uA				
Zero Gate voltage Drain Current		V_{DS} =-30V, V_{GS} = 0V, T_{J} = 100°C			-5	uA				
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20V$			±100	nA				
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1.0	-1.4	-2.5	V				
Drain Source On Begintance (note2)	В	$V_{GS} = -10V, I_{D} = -5A$		43	55	mΩ				
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = -4.5V, I_{D} = -4A$		65	90	mΩ				
Dynamic										
Input Capacitance	C _{iss}	$V_{GS} = 0V$,		580		pF				
Output Capacitance	C _{oss}	$V_{DS} = -15V$,		98						
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		74						
Total Gate Charge (4.5V)	Q_g			6.8		nC				
Gate-Source Charge	Q_{gs}	$V_{DS} = -15V, I_{D} = -5.1A,$ $V_{GS} = -10V$		1						
Gate-Drain Charge	Q_{gd}	- 65		1.4						
Turn-on Delay Time	t _{d(on)}			14		ns				
Turn-on Rise Time	t _r	$V_{DS} = -15V, I_{D} = -1A$		64						
Turn-off Delay Time	t _{d(off)}	V_{GS} =-10V, R_{G} = 2.5 Ω , R_{L} = 15 Ω		19						
Turn-off Fall Time	t _f			10						
Body Diode Characteristics										
Continuous Body Diode Current	I _S				-5.1	Α				
Pulsed Diode Forward Current	I _{SM}				-20.4	Α				
Body Diode Voltage	V_{SD} $I_{SD} = -1.7A, V_{GS} = 0V$ 1.2		V							

Notes

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width $\leq\!300\text{us}$, duty cycle $\!\leq\!2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.1mH
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



N-Channel Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted



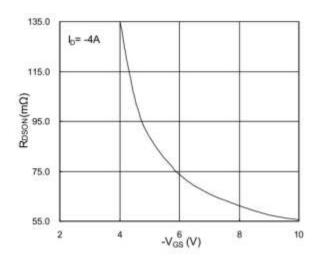


Fig.1 Typical Output Characteristics

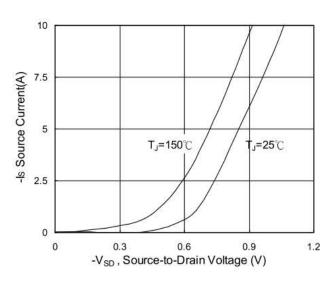


Fig.2 On-Resistance vs. G-S Voltage

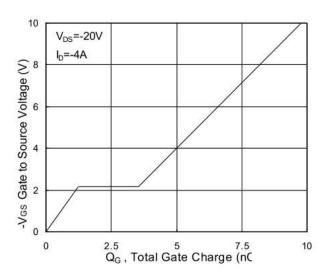
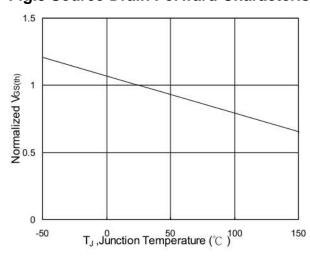


Fig.3 Source Drain Forward Characteristics Fig.4 Gate-Charge Characteristics



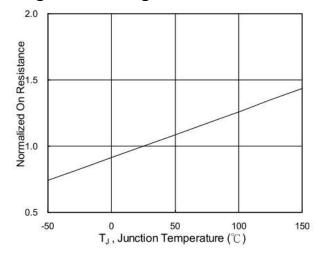


Fig.5 Normalized VGS(th) vs. TJ

Fig.6 Normalized RDSON vs. TJ

100

1000



N-Channel Typical Characteristics $T_J = 25$ °C, unless otherwise noted

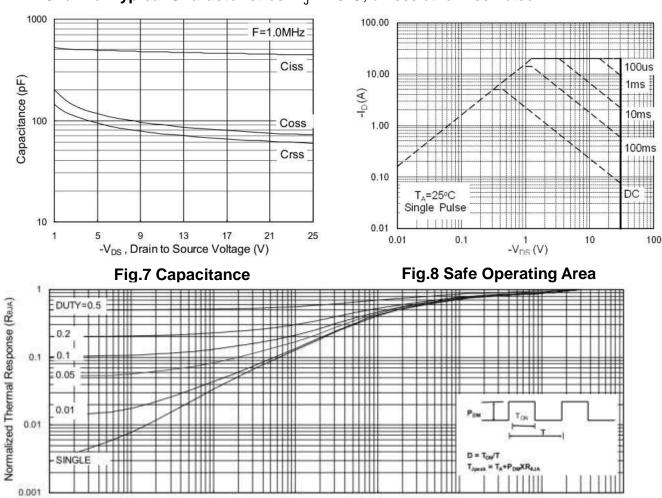


Fig.9 Normalized Maximum Transient Thermal Impedance

t, Pulse Width (s)

0.01

0.001

0.0001



Figure A: Gate Charge Test Circuit and Waveform

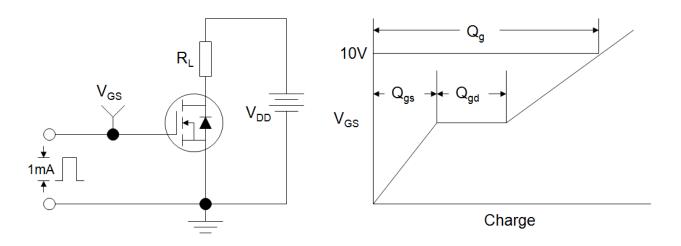


Figure B: Resistive Switching Test Circuit and Waveform

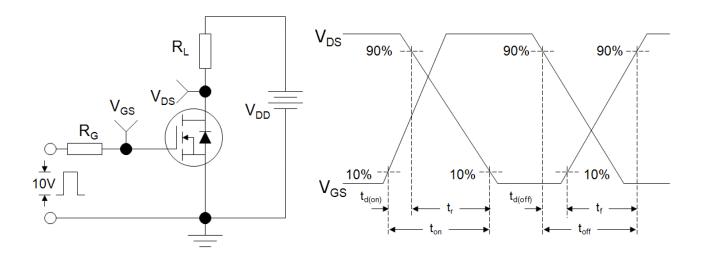
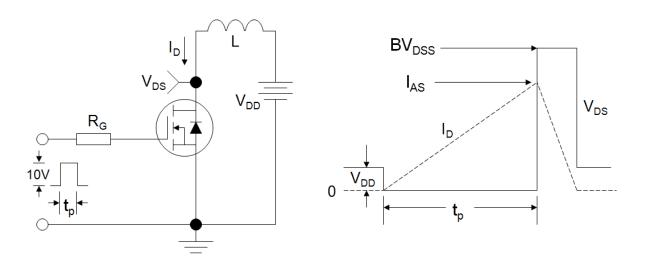
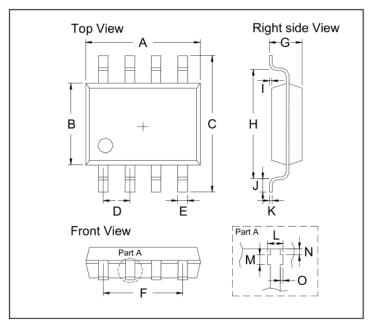


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





SOP-8



DIM	Inc	Inches		Millimeters		Inches		Millimeters	
	Min.	Max.	Min.	Max.	DIM	Min.	Max.	Min.	Max.
Α	0.1909	0.2007	4.85	5.10	I	0.0019	0.0078	0.05	0.20
В	0.1515	0.1555	3.85	3.95	J	0.0118	0.0275	0.30	0.70
С	0.2283	0.2441	5.80	6.20	K	0.0074	0.0098	0.19	0.25
D	0.0480	0.0519	1.22	1.32	L	0.0145	0.0204	0.37	0.52
E	0.0145	0.0185	0.37	0.47	М	0.0118	0.0197	0.30	0.50
F	0.1472	0.1527	3.74	3.88	N	0.0031	0.0051	0.08	0.13
G	0.0570	0.0649	1.45	1.65	0	0.0000	0.0059	0.00	0.15
Н	0.1889	0.2007	4.80	5.10					



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